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Kind regards,

Team Nexperia

1PS76SB21; BAT721 series

Schottky barrier diodes in small packages

Rev. 06 — 21 December 2006

Product data sheet

1. Product profile

1.1 General description

Planar Schottky barrier diodes with an integrated guard ring for stress protection. Encapsulated in small Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
1PS76SB21	SOD323	SC-76	single
BAT721	SOT23	-	single
BAT721A	SOT23	-	dual common anode
BAT721C	SOT23	-	dual common cathode
BAT721S	SOT23	-	dual series

1.2 Features

- Low forward voltage
- Small SMD plastic packages
- Low capacitance

1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Line termination
- Reverse polarity protection

1.4 Quick reference data


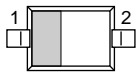
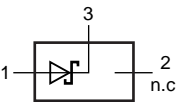
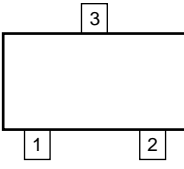
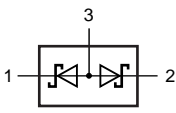
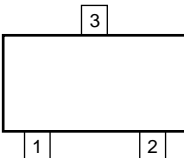
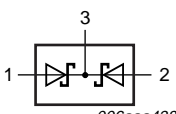
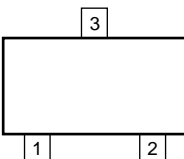
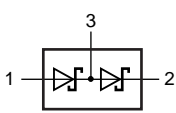
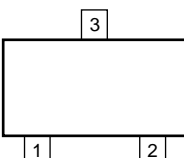
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
I_F	forward current		-	-	200	mA
V_R	reverse voltage		-	-	40	V
V_F	forward voltage	$I_F = 200 \text{ mA}$	[1]	-	550	mV

[1] Pulse test: $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
1PS76SB21			
1	cathode	[1]	1  2
2	anode		<i>sym001</i>
BAT721			
1	anode		
2	not connected		
3	cathode		
<i>006aaa436</i>			
BAT721A			
1	cathode (diode 1)		
2	cathode (diode 2)		
3	anode (diode 1), anode (diode 2)		
<i>006aaa439</i>			
BAT721C			
1	anode (diode 1)		
2	anode (diode 2)		
3	cathode (diode 1), cathode (diode 2)		
<i>006aaa438</i>			
BAT721S			
1	anode (diode 1)		
2	cathode (diode 2)		
3	cathode (diode 1), anode (diode 2)		
<i>006aaa437</i>			
<i>006aaa144</i>			

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
1PS76SB21	SC-76	plastic surface-mounted package; 2 leads	SOD323
BAT721	-	plastic surface-mounted package; 3 leads	SOT23
BAT721A			
BAT721C			
BAT721S			

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
1PS76SB21	S1
BAT721	L7*
BAT721A	L8*
BAT721C	L9*
BAT721S	L0*

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V_R	reverse voltage		-	40	V
I_F	forward current		-	200	mA
I_{FSM}	non-repetitive peak forward current	half sine wave; JEDEC method; $t_p = 8.3$ ms	-	1	A
T_j	junction temperature		-	125	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	1PS76SB21		-	-	450	K/W
	BAT721		-	-	500	K/W
	BAT721A		-	-	500	K/W
	BAT721C		-	-	500	K/W
	BAT721S		-	-	500	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

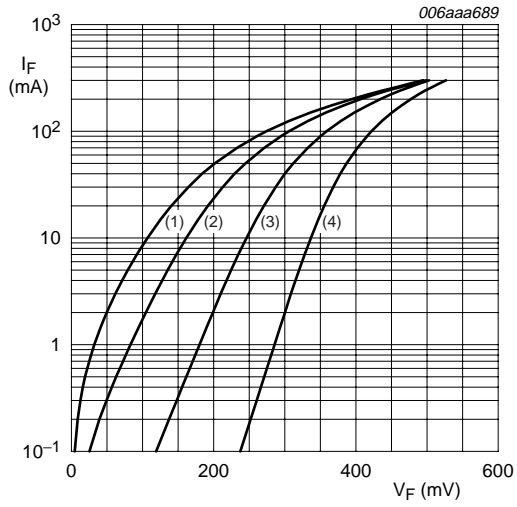
7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

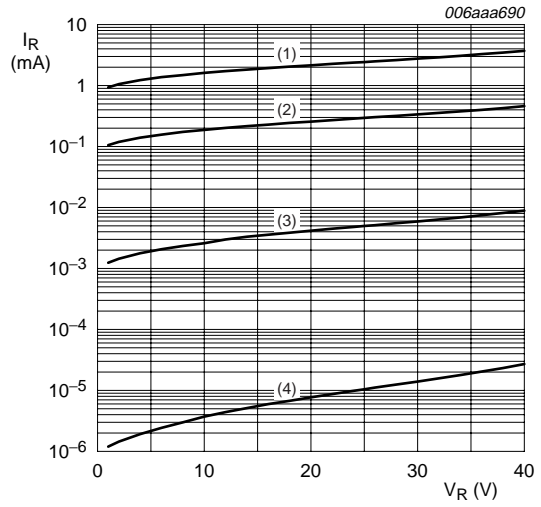
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_F	forward voltage	$I_F = 10\text{ mA}$	[1]	-	300	mV
		$I_F = 100\text{ mA}$	[1]	-	420	mV
		$I_F = 200\text{ mA}$	[1]	-	550	mV
I_R	reverse current	$V_R = 30\text{ V}$	-	-	15	μA
		$V_R = 30\text{ V}; T_j = 100\text{ }^{\circ}\text{C}$	-	-	3	mA
C_d	diode capacitance	$V_R = 0\text{ V}; f = 1\text{ MHz}$	-	40	50	pF

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.



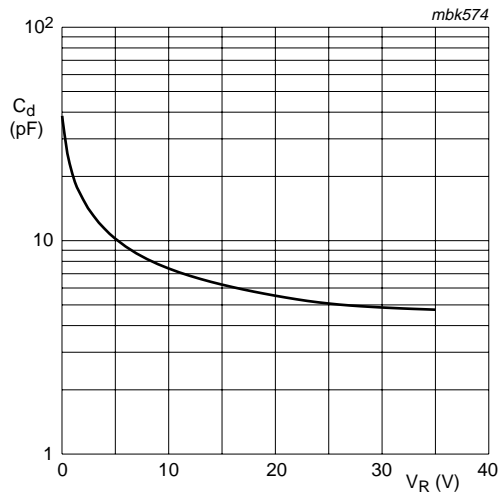
- (1) $T_{\text{amb}} = 125^\circ\text{C}$
- (2) $T_{\text{amb}} = 85^\circ\text{C}$
- (3) $T_{\text{amb}} = 25^\circ\text{C}$
- (4) $T_{\text{amb}} = -40^\circ\text{C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1) $T_{\text{amb}} = 125^\circ\text{C}$
- (2) $T_{\text{amb}} = 85^\circ\text{C}$
- (3) $T_{\text{amb}} = 25^\circ\text{C}$
- (4) $T_{\text{amb}} = -40^\circ\text{C}$

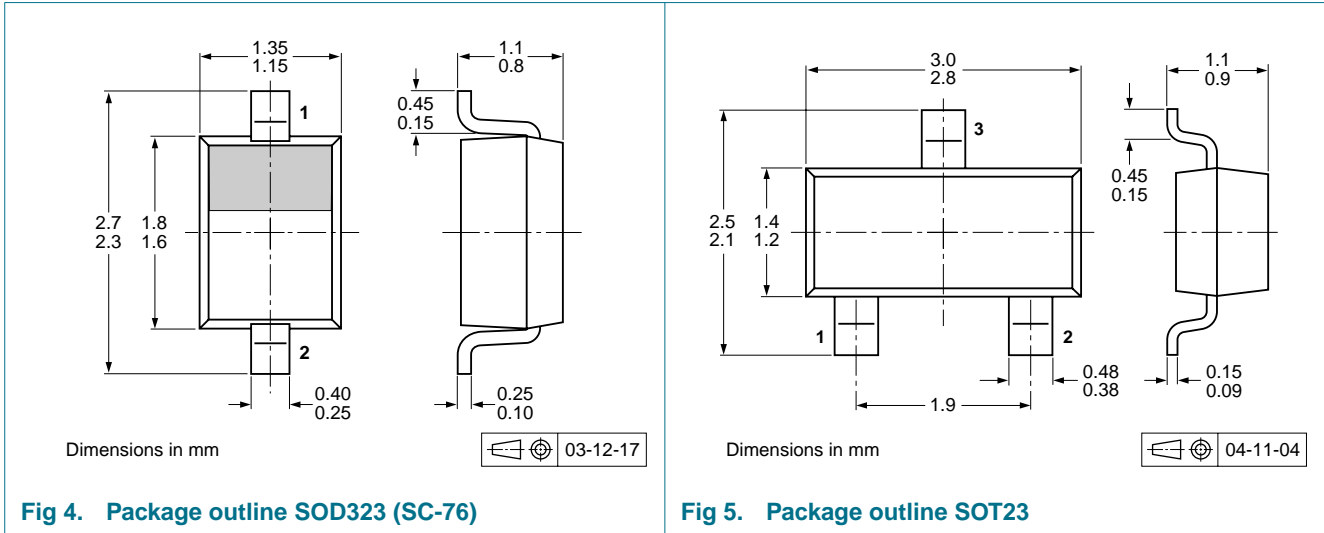
Fig 2. Reverse current as a function of reverse voltage; typical values



$T_{\text{amb}} = 25^\circ\text{C}; f = 1\text{ MHz}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Package outline



9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
1PS76SB21	SOD323	4 mm pitch, 8 mm tape and reel	-115	-135
BAT721	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
BAT721A				
BAT721C				
BAT721S				

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering

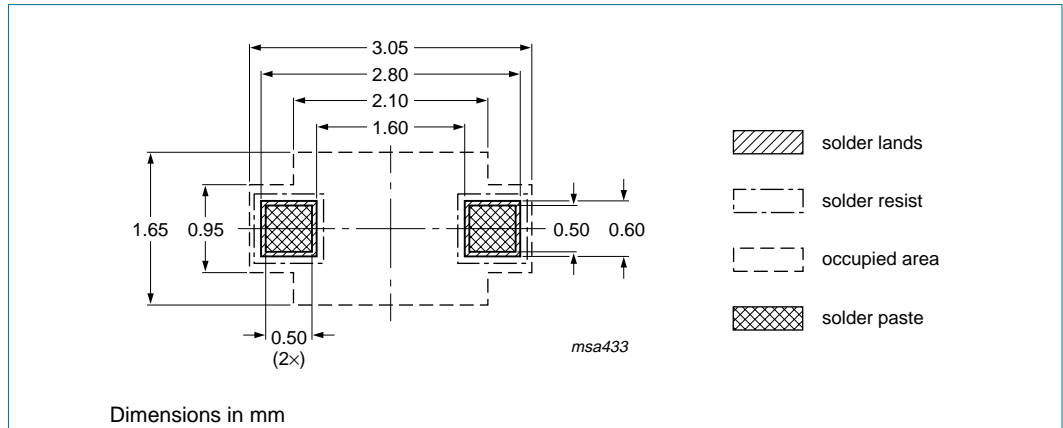


Fig 6. Reflow soldering footprint SOD323 (SC-76)

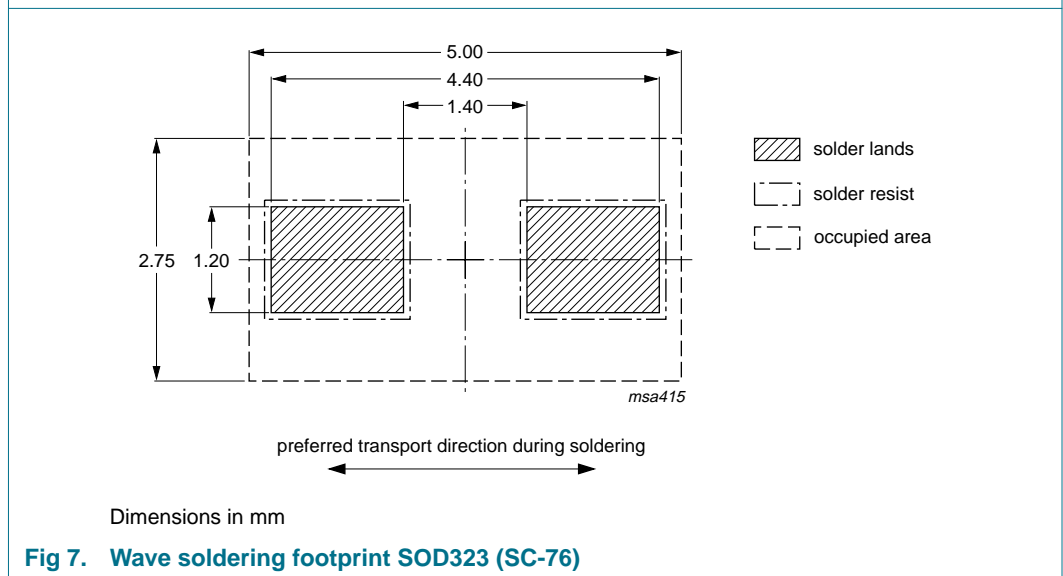


Fig 7. Wave soldering footprint SOD323 (SC-76)

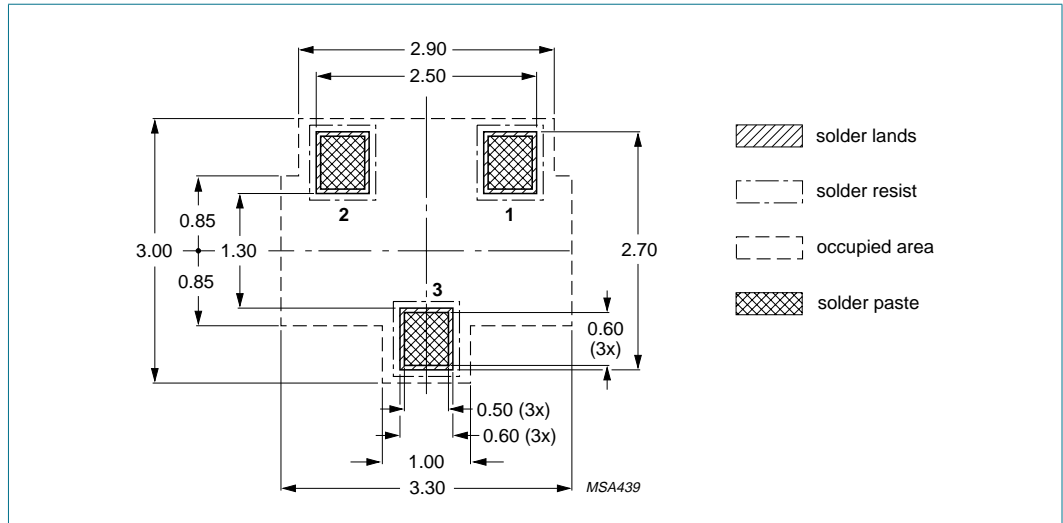


Fig 8. Reflow soldering footprint SOT23

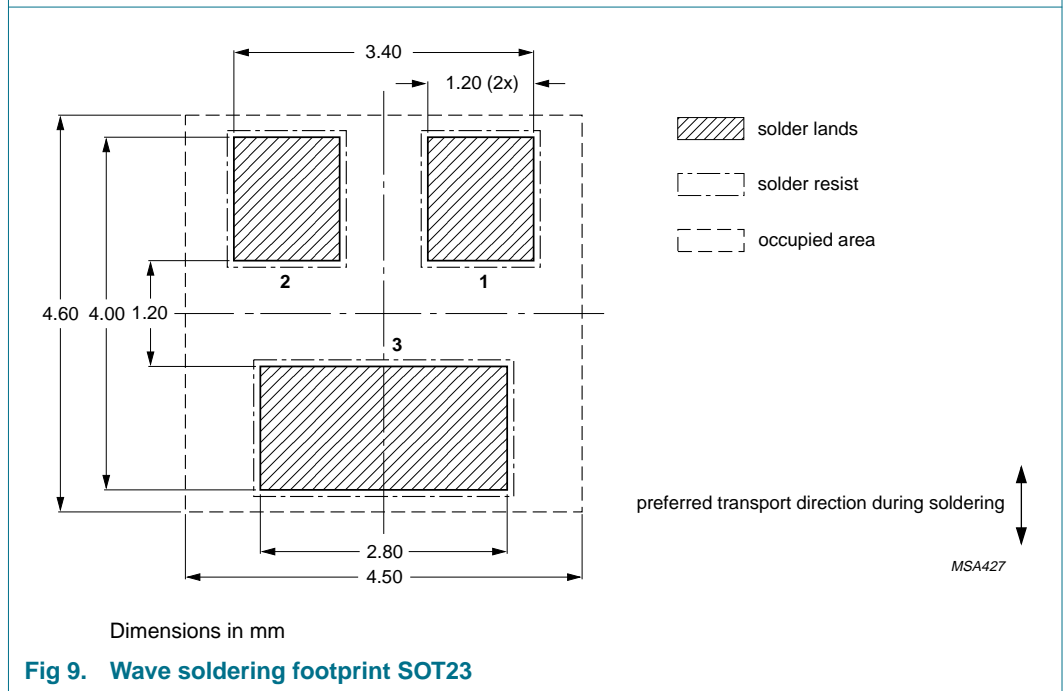


Fig 9. Wave soldering footprint SOT23

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
1PS76SB21_BAT721_SER_6	20061221	Product data sheet	-	1PS76SB21_BAT721_SER_5
Modifications:	<ul style="list-style-type: none"> Amended Table 10 "Revision history" 			
1PS76SB21_BAT721_SER_5	20061205	Product data sheet	-	BAT721_SERIES_4 1PS76SB21_3
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. This data sheet is a combination of data sheets BAT721_SERIES_4 and 1PS76SB21_3. Table 1 "Product overview": added Section 1.2 "Features": amended Section 1.3 "Applications": amended Table 2 "Quick reference data": added Table 5 "Marking codes": for 1PS76SB21 amended Table 5 "Marking codes": enhanced table note section Table 6 "Limiting values": indication per diode added Table 6 "Limiting values": for 1PS76SB21 I_{FSM} condition amended Table 6 "Limiting values": T_{amb} ambient temperature added Table 7 "Thermal characteristics": indication per diode added Table 7: $R_{th(j-a)}$ thermal resistance from junction to ambient condition amended Table 8 "Characteristics": indication per diode added Table 8 "Characteristics": reference to Table note 1 amended Table 8: for 1PS76SB21 C_d minimum value changed to typical value Figure 1 and 2: amended Figure 4 and 5: superseded by minimized package outlines Section 9 "Packing information": added Section 10 "Soldering": added Section 12 "Legal information": updated 			
BAT721_SERIES_4	20040315	Product specification	-	BAT721_SERIES_3
1PS76SB21_3	20040126	Product specification	-	1PS76SB21_2

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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